

Standard 6" Wafer Adhesive Tape Specification

Standard Adhesive Tape Parameters

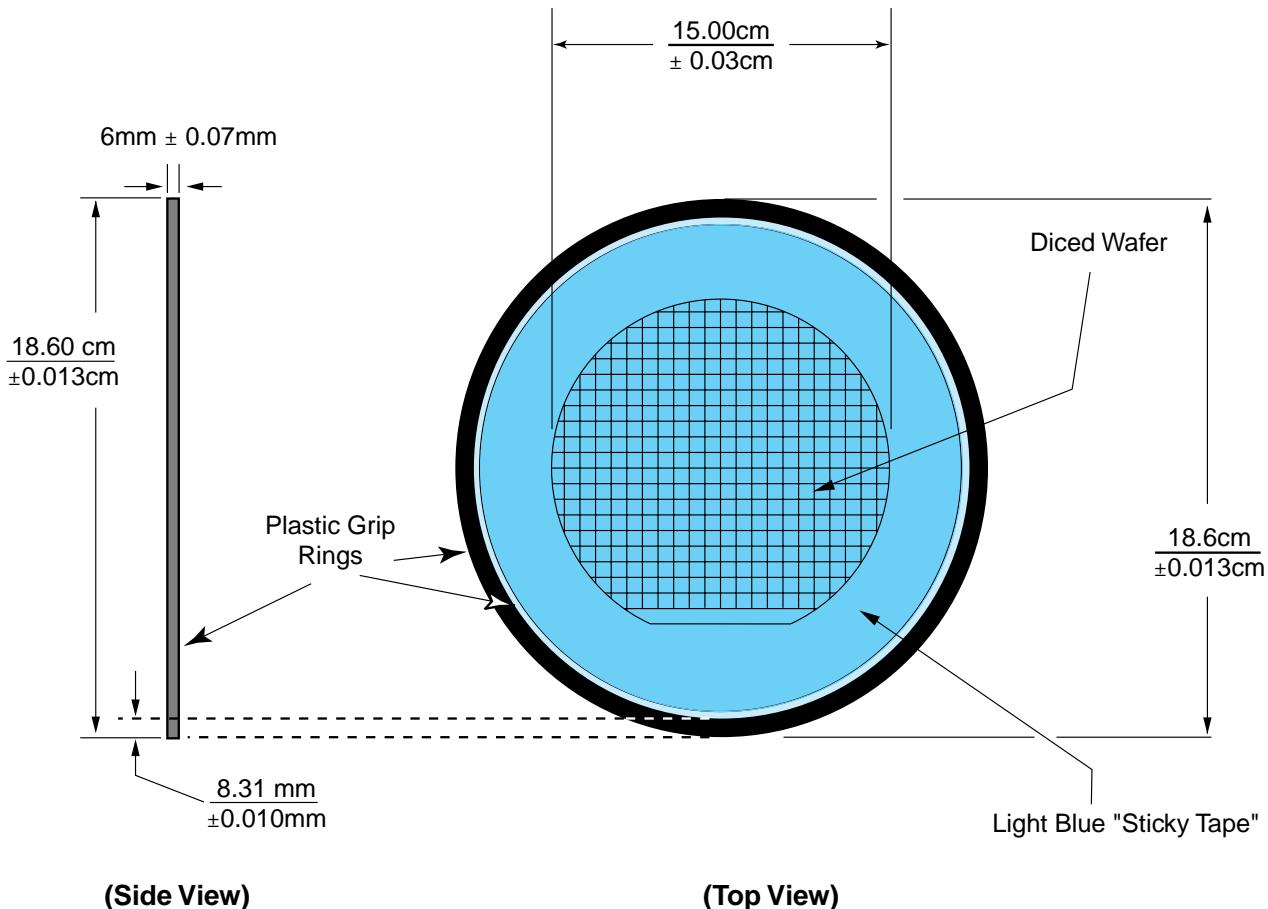
Material:	Light Blue Anti-Static Plastic Tape/Plastic Grip Rings
Tape Thickness:	0.055mm to 0.085mm
Ring Height:	6mm \pm 0.07mm
Ring Diameter:	18.6cm \pm 0.013cm
Elongation at Breaking Point:	3.0kg/20mm
Shape:	Circle

General Description

The wafer frame for the blue sticky tape is prepared by clamping two concentric plastic rings together. Whole wafers are mounted onto the wafer frame. The wafer is then sawn into individual dice which retain their original position in the wafer matrix, inspected and packaged in protective containers for shipment. This cost effective method is useful in pick and place assembly (using a plunge up scheme) as well as small volume laboratory experiments.

Ordering Information

To designate this packaging option, package type NJ must be called out for any DMOS product (e.g. TN2524NJ), and package type XJ must be called out for any HVC MOS product (e.g. HV57708XJ).



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